#### DISCRETE SEMICONDUCTORS







Product specification
Supersedes data of May 1993







BYV98

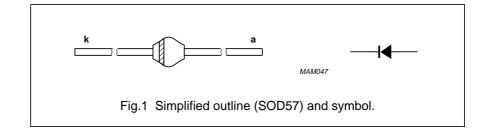
#### **FEATURES**

- · Glass passivated
- High maximum operating temperature
- · Low leakage current
- Excellent stability
- Available in ammo-pack.

#### **DESCRIPTION**

Rugged glass SOD57 package, using a high temperature alloyed

construction. This package is hermetically sealed and fatigue free as coefficients of expansion of all used parts are matched.



#### **LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>RSM</sub>	non-repetitive peak reverse voltage		_	2100	V
V <sub>RRM</sub>	repetitive peak reverse voltage		_	2000	V
I <sub>F(AV)</sub>	average forward current	T <sub>tp</sub> = 55 °C; lead length = 10 mm see Fig. 2; averaged over any 20 ms period; see also Fig. 6	_	1.00	A
I <sub>F(AV)</sub>	average forward current	T <sub>amb</sub> = 60 °C; PCB mounting (see Fig.11); see Fig. 3; averaged over any 20 ms period; see also Fig. 6	_	0.43	A
I <sub>FRM</sub>	repetitive peak forward current	T <sub>tp</sub> = 55 °C; see Fig. 4	_	9.0	А
		T <sub>amb</sub> = 60 °C; see Fig. 5	_	4.5	А
I <sub>FSM</sub>	non-repetitive peak forward current	t = 10 ms half sine wave; $T_j = T_{j \text{ max}}$ prior to surge; $V_R = V_{RRMmax}$	_	15	А
T <sub>stg</sub>	storage temperature		-65	+175	°C
Tj	junction temperature	see Fig.7	-65	+175	°C

2

Philips Semiconductors Product specification

# Fast soft-recovery rectifier

BYV98

#### **ELECTRICAL CHARACTERISTICS**

 $T_i = 25$  °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V <sub>F</sub>	forward voltage	$I_F = 2 A$ ; $T_j = T_{j \text{ max}}$ ; see Fig. 8	_	_	2.2	V
		I <sub>F</sub> = 2 A; see Fig. 8	_	_	2.4	V
I <sub>R</sub>	reverse current	V <sub>R</sub> = V <sub>RRMmax</sub> ; see Fig. 9	_	_	5	μΑ
		$V_R = V_{RRMmax}$ ; $T_j = 125  ^{\circ}C$ ; see Fig. 9	_	-	50	μΑ
t <sub>rr</sub>	reverse recovery time	when switched from $I_F = 0.5 \text{ A}$ to $I_R = 1 \text{ A}$ ; measured at $I_R = 0.25 \text{ A}$ ; see Fig. 12	_	-	300	ns
C <sub>d</sub>	diode capacitance	f = 1 MHz; V <sub>R</sub> = 0 V; see Fig 10	_	30	_	pF
$\left  \frac{dI_R}{dt} \right $	maximum slope of reverse recovery current	when switched from $I_F$ = 1 A to $V_R \ge 30$ V and $dI_F/dt$ = $-1$ A/ $\mu$ s; see Fig.13	-	-	5	A/μs

#### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th j-tp</sub>	thermal resistance from junction to tie-point	lead length = 10 mm	46	K/W
R <sub>th j-a</sub>	thermal resistance from junction to ambient	note 1	100	K/W

#### Note

1. Device mounted on an epoxy-glass printed-circuit board, 1.5 mm thick; thickness of Cu-layer ≥40 μm, see Fig.11. For more information please refer to the "General Part of associated Handbook".

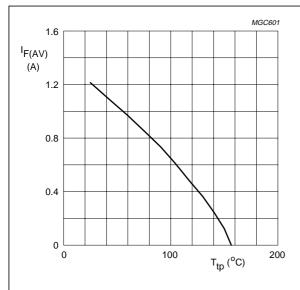
3

Philips Semiconductors Product specification

## Fast soft-recovery rectifier

BYV98

#### **GRAPHICAL DATA**



 $a = 1.42; \ V_R = V_{RRMmax}; \ \delta = 0.5.$  Switched mode application.

Fig.2 Maximum permissible average forward current as a function of tie-point temperature (including losses due to reverse leakage).

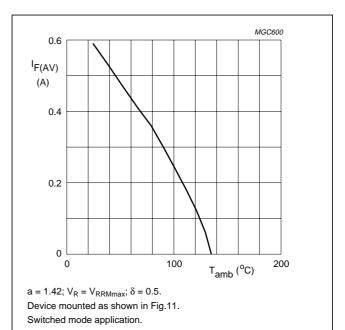
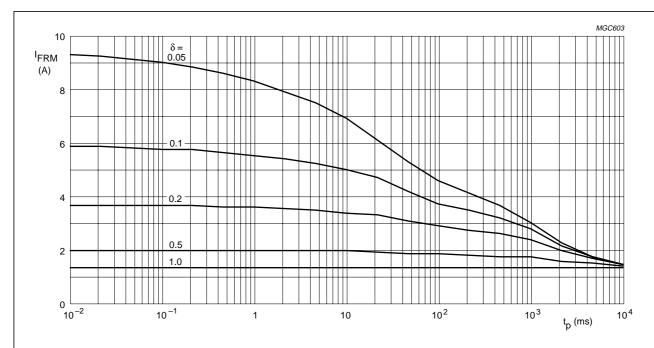


Fig.3 Maximum permissible average forward current as a function of ambient temperature (including losses due to reverse leakage).



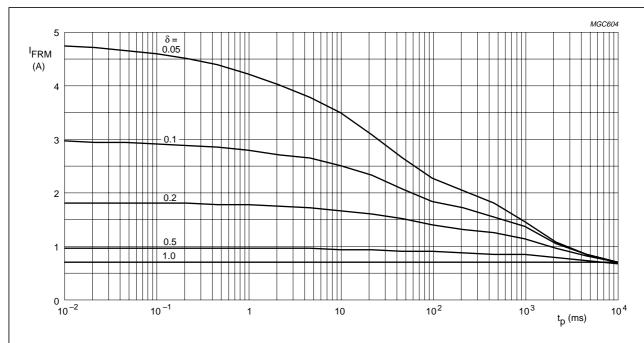
 $T_{tp} = 55^{\circ}C$ ;  $R_{th j-tp} = 46$  K/W.

 $V_{RRMmax}$  during 1 –  $\delta$ ; curves include derating for  $T_{j max}$  at  $V_{RRM}$  = 2000 V.

Fig.4 Maximum repetitive peak forward current as a function of pulse time (square pulse) and duty factor.

1996 Jun 07 4

BYV98



 $T_{amb}$  = 60 °C;  $R_{th\ j\text{-}a}$  = 100 K/W.

 $V_{RRMmax}$  during 1 –  $\delta$ ; curves include derating for  $T_{j\,max}$  at  $V_{RRM}$  = 2000 V.

Fig.5 Maximum repetitive peak forward current as a function of pulse time (square pulse) and duty factor.

5

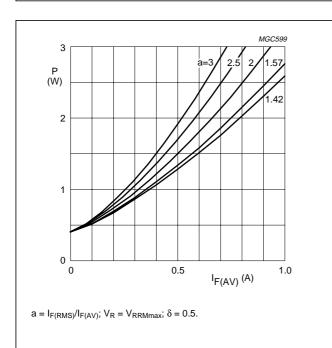


Fig.6 Maximum steady state power dissipation (forward plus leakage current losses, excluding switching losses) as a function of average forward current.

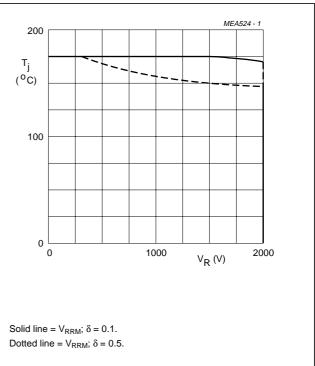
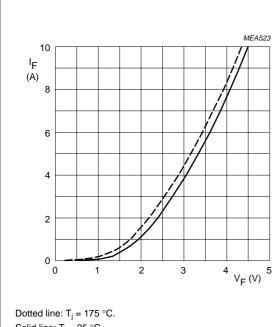


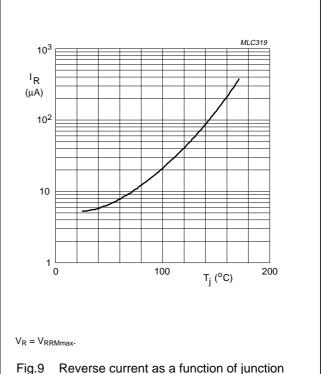
Fig.7 Maximum permissible junction temperature as a function of reverse voltage.

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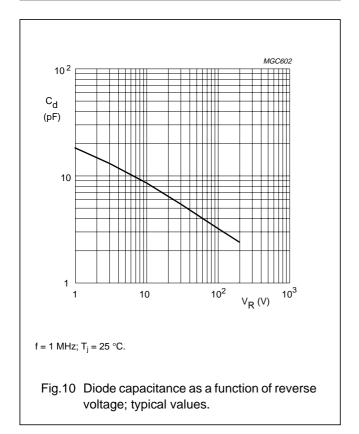


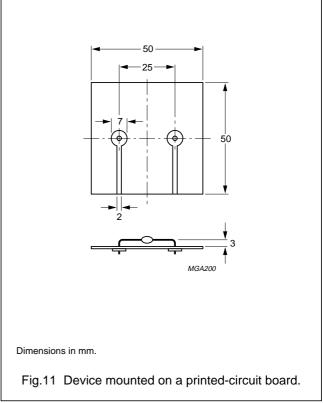
Solid line:  $T_j = 25 \,^{\circ}\text{C}$ .

Fig.8 Forward current as a function of forward voltage; maximum values.



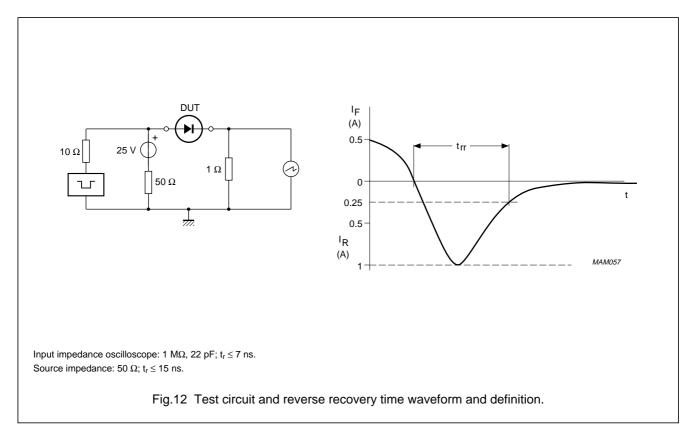
temperature; maximum values.



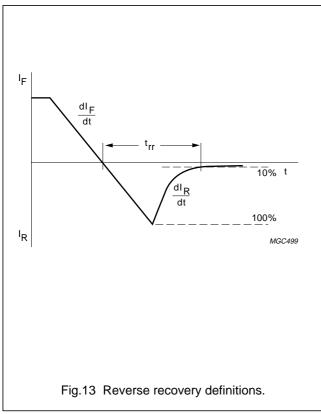


1996 Jun 07 6

BYV98



7

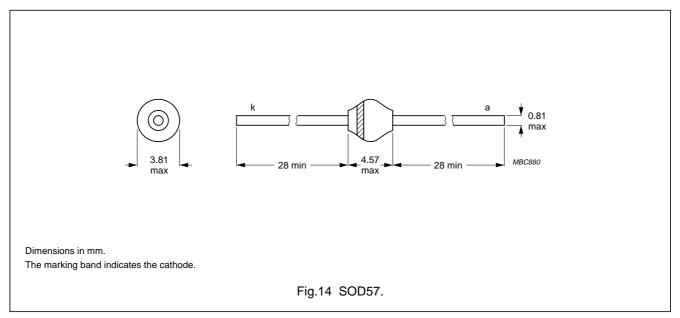


Philips Semiconductors Product specification

### Fast soft-recovery rectifier

BYV98

#### **PACKAGE OUTLINE**



#### **DEFINITIONS**

Data Sheet Status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limitina values	

#### **Limiting values**

Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

#### **Application information**

Where application information is given, it is advisory and does not form part of the specification.

#### LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.

8